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PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date	
Yu-Min Lin	04/18/2012	
Chau-Jie Zhan	04/18/2012	
Tao-Chih Chang	04/18/2012	

RECEIVING PARTY DATA

Name:	Industrial Technology Research Institute	
Street Address:	No. 195, Sec. 4, Chung Hsing Rd., Chutung,	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	31040	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	13484289	

CORRESPONDENCE DATA

Fax Number: (510)580-7280

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: Jianq Chyun Intellectual Property Office
Address Line 1: 7F.-1, NO. 100, ROOSEVELT RD., SEC. 2,

Address Line 4: Taipei, TAIWAN 100

ATTORNEY DOCKET NUMBER: 40298-US-PA

NAME OF SUBMITTER: Belinda Lee

Total Attachments: 2

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PATENT

REEL: 028300 FRAME: 0453

\$40.00 1348

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ASSIGNMENT

WHEREAS

1. Yu-Min Lin

2. Chau-Jie Zhan

3. Tao-Chih Chang

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: BUMP STRUCTURE AND ELECTRONIC PACKAGING SOLDER JOINT STRUCTURE AND FABRICATING METHOD THEREOF

[] Filed:

Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute

of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMON'	Y WHEREOF	, Assignor	has/have	signed his/he	r/their	name(s)	on the	date(s)
indicated.								

Signature: Yu - Min Lin	Date: 4, 18, 2012
Sole or First Joint Inventor: Yu-Min Lin	
signature: Chau-Jie Zhan	Date: 04 (8. 20/2
Second Joint Inventor (if any): Chau-Jie Zhan	
Signature: Too-Click Char	9 Date: 04.18.2012

Third Joint Inventor (if any): Tao-Chih Chang